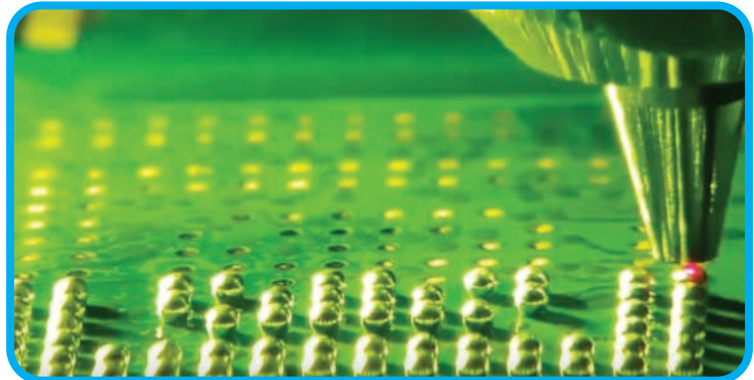
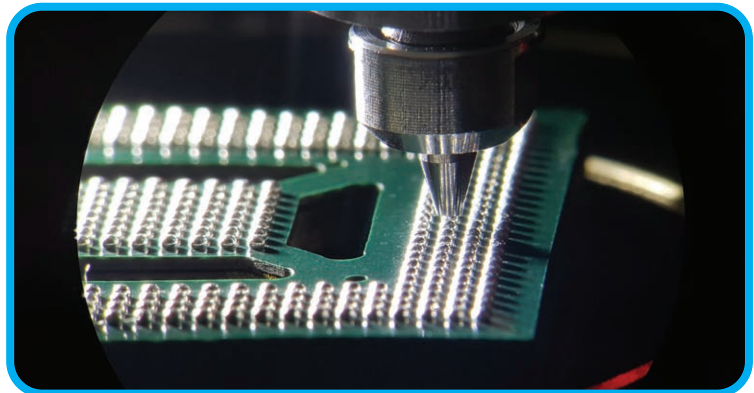
LASER REBALLING

Retronix sets a new benchmark with the most advanced and reliable reballing process.

Retronix are the only company to offer Laser Reballing, eliminating additional reflow for a safer process.



This system provides reproducible solder bumping technology for BGA's, CLCC's, CSP's, Flip Chips and many more.



With the latest laser technology this gives Retronix the ability to laser high melt solder balls (HMP), Sn 63/37, SAC 305 down to 250 microns.

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RETRONIX

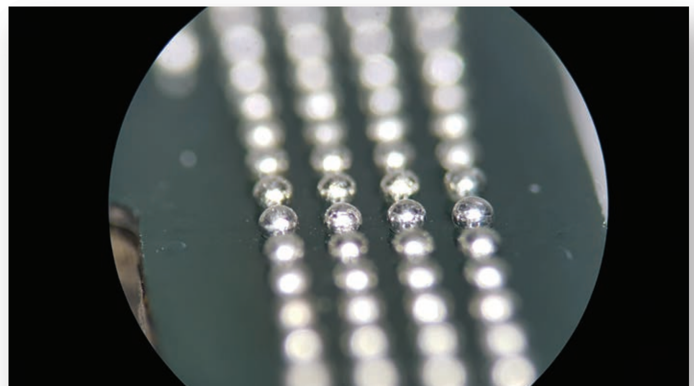
LASER REBALLING

FEATURES & BENEFITS:

- Single-step solder ball placement and reflow
- Flux-free reflow with laser
- No additional reflow required
- Solder-ball diameter from – 250μm to 760μm
- High solder alloy flexibility – Eutectic SnPb,
- High-lead SnPb, Lead-free SnAg, SnAgCu, etc.
- In-line capability & High throughput
- High accuracy axis system
- Automated fiducial alignment
- Ball rework and repair capability
- 3D Camera – Height auto measurement
- 2D bump-inspection systems
- Integrated laser power sensor
- Solder rework & reballing station
- Automatic handling/robot system

APPLICATIONS:

- HDD (HGA, HSA, Hook-Up)
- Flip-chip, BGAs, CLCC's, CSPs
- 3D packaging
- 4- to 12-inch wafers
- Repair/rework of BGA-like packages
- Optoelectronics/Micro-optics
- MEMS
- Camera modules
- Wafer bumping



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